In situ synchrotron study of electromigration induced grain rotation in anisotropic Sn solder joints

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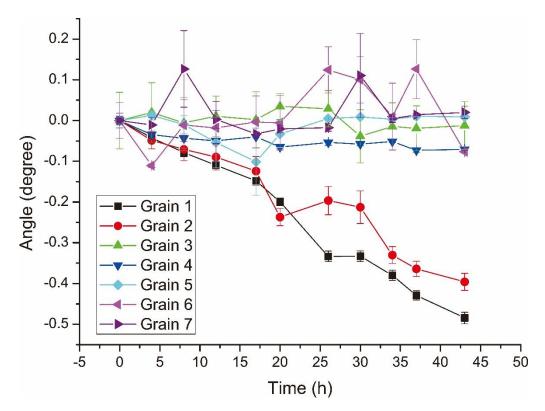


Figure S1. The evolution of θ_a , which is defined as the angle between the crystal *a*-axis and current direction. Comparing with Figure 2 in main text, it is concluded that the rotation of Grain 2 is almost about its *c*-axis.

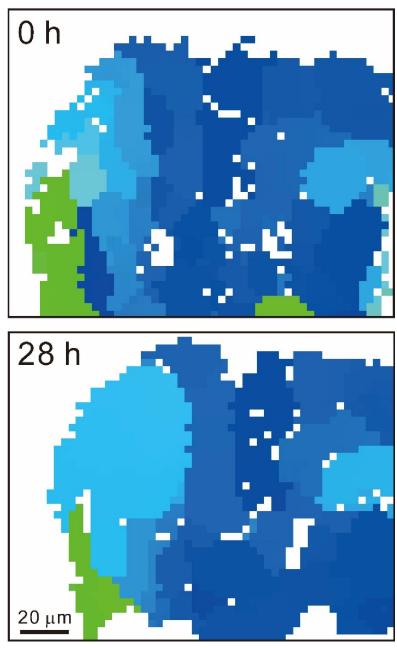


Figure S2. The orientation maps of an identical solder joint before and after 28 h EM test at 150 °C. The crystal grains grow much bigger in this period.